

Product Summary

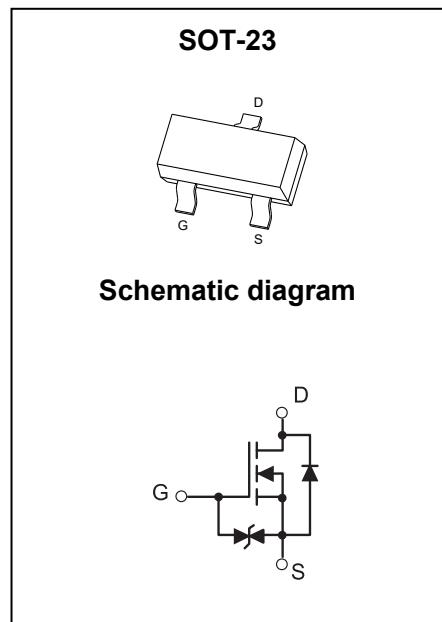
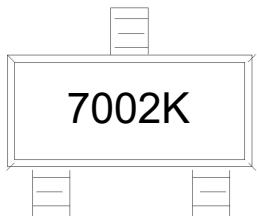
$V_{(BR)DSS}$	$R_{DS(on)}TYP$	I_D
60V	0.9Ω@10V	0.34A
	1.1Ω@4.5V	

Feature

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- ESD Protected

Application

- Load Switch
- DC/DC Converter

MARKING:**ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain - Source Voltage	V_{DS}	60	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^{1,5}	I_D	0.34	A
Pulsed Drain Current ²	I_{DM}	1.0	A
Power Dissipation ^{4,5}	P_D	0.35	W
Thermal Resistance from Junction to Ambient ⁵	$R_{\theta JA}$	357	°C/W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55~ +150	°C

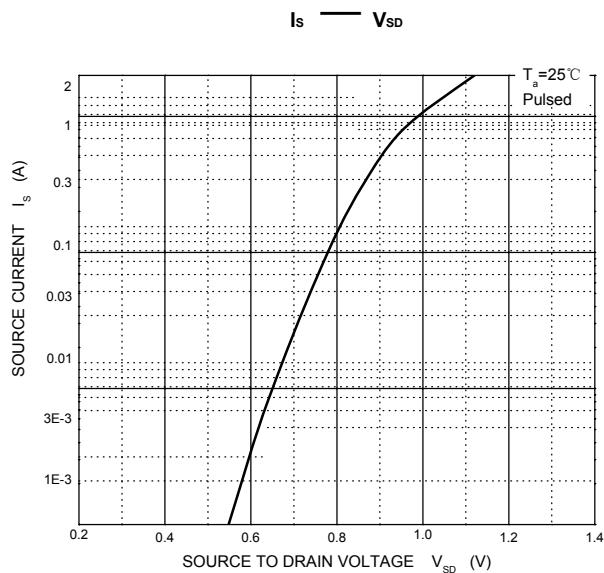
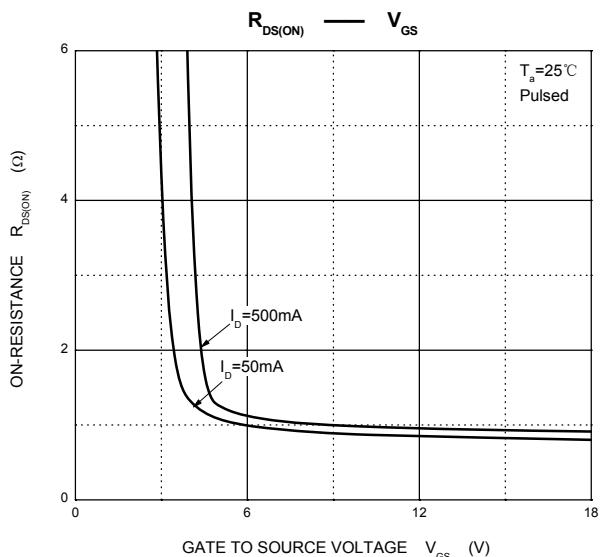
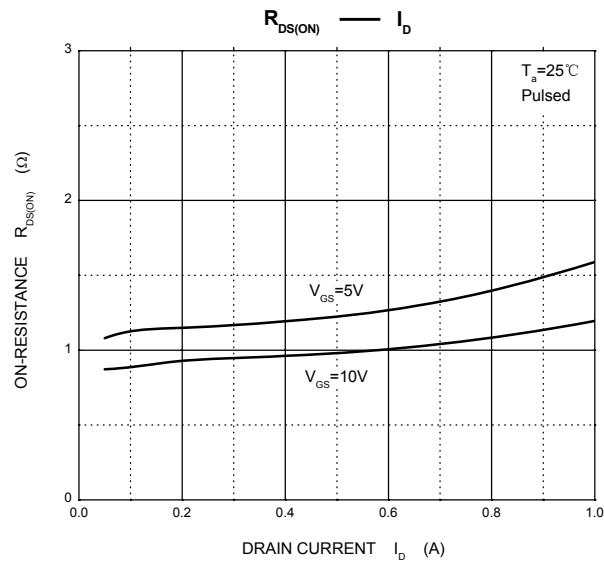
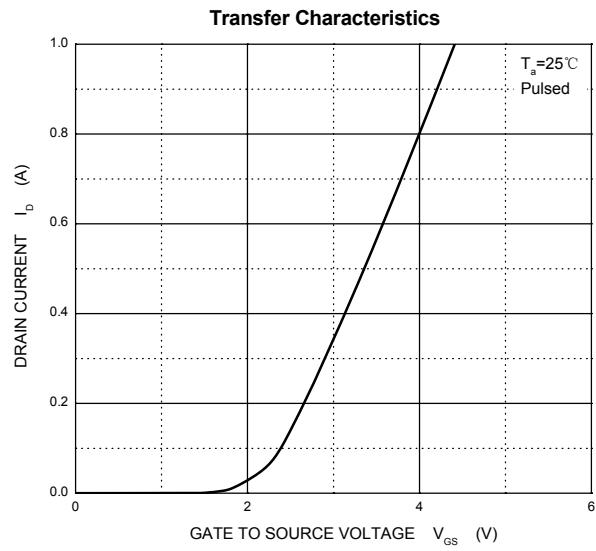
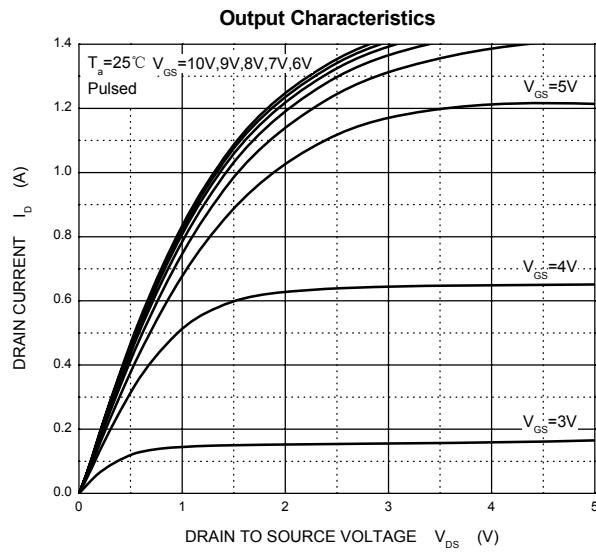
MOSFET ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

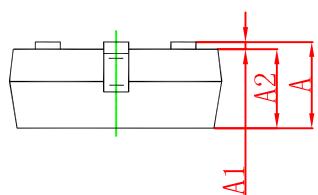
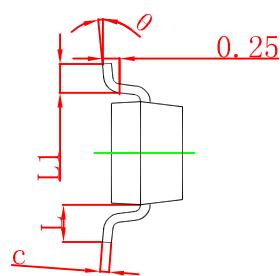
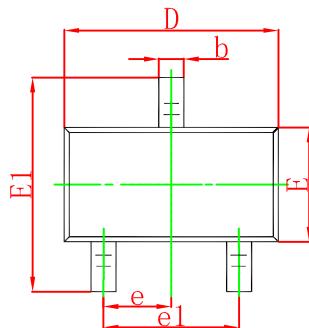
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	60			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 48\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate - Body Leakage Current	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$			± 5	μA
On Characteristics³						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1	1.5	2.5	V
Drain-source On-resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 0.3\text{A}$		0.9	2.5	Ω
		$V_{\text{GS}} = 4.5\text{V}, I_D = 0.2\text{A}$		1.1	3	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		23.7		pF
Output Capacitance	C_{oss}			5.3		
Reverse Transfer Capacitance	C_{rss}			2.5		
Gate Resistance	R_g	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		160		Ω
Switching Characteristics						
Total Gate Charge	Q_g	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 0.3\text{A}$		0.29		nC
Gate-source Charge	Q_{gs}			0.23		
Gate-drain Charge	Q_{gd}			0.12		
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{\text{DD}} = 30\text{V}, V_{\text{GS}} = 10\text{V}, R_L = 100\Omega, R_G = 3\Omega$		3.5		ns
Turn-on Rise Time	t_r			3.2		
Turn-off Delay Ttime	$t_{d(\text{off})}$			12		
Turn-off Fall Time	t_f			10		
Source - Drain Diode Characteristics						
Diode Forward Voltage ³	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_s = 0.3\text{A}$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.
- 2.Pulse Test : Pulse Width $\leq 10\mu\text{s}$, duty cycle $\leq 1\%$.
- 3.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- 4.The power dissipation P_D is limited by $T_{J(\text{MAX})} = 150^\circ\text{C}$.
- 5.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

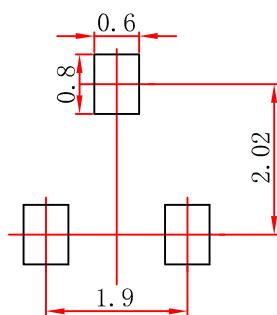
Typical Characteristics





Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.